



SEMITRANS® 3

Trench IGBT Modules

SKM400GB07E3

Features*

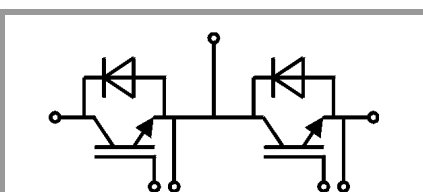
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Fast & soft switching inverse CAL diodes
- Insulated copper baseplate using DCB Technology (Direct Copper Bonding)
- With integrated gate resistor

Typical Applications

- AC inverter drives
- UPS
- Electronic welders

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max.
- Recommended $T_{op} = -40 \dots +150^\circ\text{C}$
- Product reliability results valid for $T_j = 150^\circ\text{C}$
- Use of soft R_G necessary



GB

Absolute Maximum Ratings						
Symbol	Conditions		Values		Unit	
IGBT						
V _{CES}	T _j = 25 °C		650		V	
I _C	T _j = 175 °C	T _c = 25 °C	506		A	
		T _c = 80 °C	381		A	
I _{Cnom}			400		A	
I _{CRM}	I _{CRM} = 3 x I _{Cnom}		1200		A	
V _{GES}			-20 ... 20		V	
t _{psc}	V _{CC} = 360 V V _{GE} ≤ 15 V V _{CES} ≤ 650 V	T _j = 150 °C	6		µs	
T _j			-40 ... 175		°C	
Inverse diode						
V _{RRM}	T _j = 25 °C		650		V	
I _F	T _j = 175 °C	T _c = 25 °C	447		A	
		T _c = 80 °C	324		A	
I _{Fnom}			400		A	
I _{FRM}	I _{FRM} = 2 x I _{Fnom}		800		A	
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		2646		A	
T _j			-40 ... 175		°C	
Module						
I _{t(RMS)}			500		A	
T _{stg}	module without TIM		-40 ... 125		°C	
V _{isol}	AC sinus 50 Hz, t = 1 min		4000		V	
Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 400 A V _{GE} = 15 V chipelevel	T _j = 25 °C	1.45	1.92		V
		T _j = 150 °C	1.70	2.10		V
V _{CE0}	chipelevel	T _j = 25 °C	0.90	1.00		V
		T _j = 150 °C	0.82	0.90		V
r _{CE}	V _{GE} = 15 V chipelevel	T _j = 25 °C	1.38	2.3		mΩ
		T _j = 150 °C	2.2	3.0		mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 6.4 mA		5.1	5.8	6.4	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 650 V, T _j = 25 °C				0.8	mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz	24.7			nF
C _{oes}		f = 1 MHz	1.54			nF
C _{res}		f = 1 MHz	0.73			nF
Q _G	V _{GE} = - 8 V...+ 15 V		3200			nC
R _{Gint}	T _j = 25 °C		1.0			Ω
t _{d(on)}	V _{CC} = 300 V	T _j = 150 °C	190			ns
t _r	I _C = 400 A	T _j = 150 °C	60			ns
E _{on}	V _{GE} = +15/-7.5 V R _{G on} = 1 Ω	T _j = 150 °C	4			mJ
t _{d(off)}	R _{G off} = 4.2 Ω	T _j = 150 °C	850			ns
t _f	di/dt _{on} = 7000 A/µs di/dt _{off} = 5000 A/µs	T _j = 150 °C	50			ns
E _{off}	dv/dt = 2200 V/µs L _s = 18 nH	T _j = 150 °C	17			mJ
R _{th(j-c)}	per IGBT				0.12	K/W
R _{th(c-s)}	per IGBT (λ _{grease} =0.81 W/(m²K))			0.04		K/W
R _{th(c-s)}	per IGBT, pre-applied phase change material			0.033		K/W



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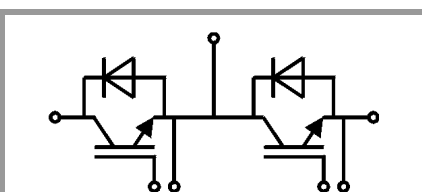
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 400 A	T _j = 25 °C		1.39	1.75	V
	V _{GE} = 0 V chipelevel	T _j = 150 °C		1.38	1.76	V
V _{F0}	chipelevel	T _j = 25 °C		1.04	1.24	V
		T _j = 150 °C		0.85	0.99	V
r _F	chipelevel	T _j = 25 °C		0.88	1.30	mΩ
		T _j = 150 °C		1.32	1.93	mΩ
I _{RRM}	I _F = 400 A	T _j = 150 °C		459		A
Q _{rr}	di/dt _{off} = 7000 A/μs	T _j = 150 °C		61		μC
E _{rr}	V _{GE} = -7.5 V V _{CC} = 300 V	T _j = 150 °C		12		mJ
R _{th(j-c)}	per diode				0.191	K/W
R _{th(c-s)}	per diode (λ _{grease} =0.81 W/(m*K))			0.041		K/W
R _{th(c-s)}	per diode, pre-applied phase change material			0.036		K/W
Module						
L _{CE}				15		nH
R _{CC'+EE'}	measured per switch	T _C = 25 °C		0.55		mΩ
		T _C = 125 °C		0.85		mΩ
R _{th(c-s)1}	calculated without thermal coupling (λ _{grease} =0.81 W/(m*K))			0.0101		K/W
R _{th(c-s)2}	including thermal coupling, T _s underneath module (λ _{grease} =0.81 W/(m*K))			0.017		K/W
R _{th(c-s)2}	including thermal coupling, T _s underneath module, pre-applied phase change material			0.014		K/W
M _s	to heat sink M6		3		5	Nm
M _t		to terminals M6	2.5		5	Nm
						Nm
w					325	g



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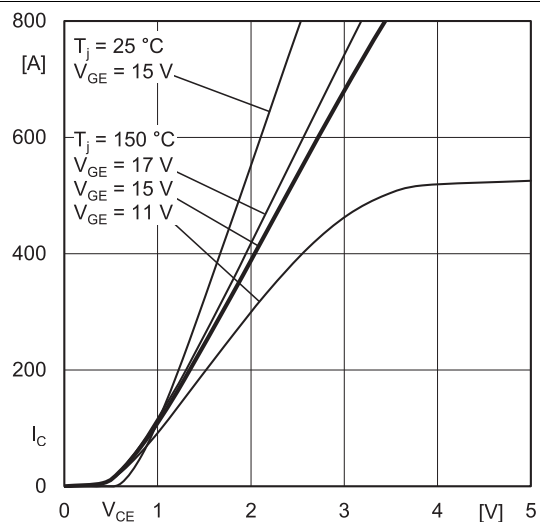


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_E$

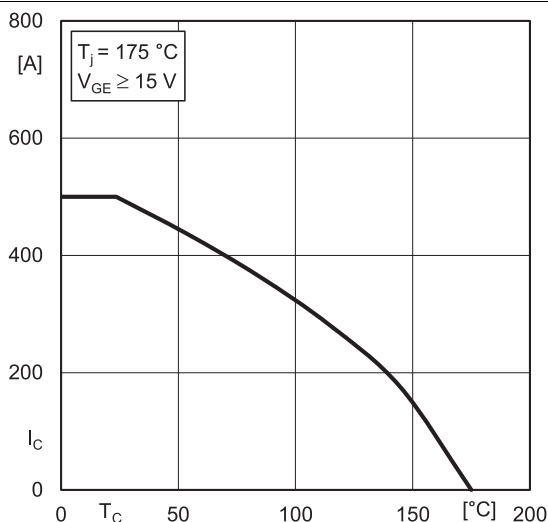


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

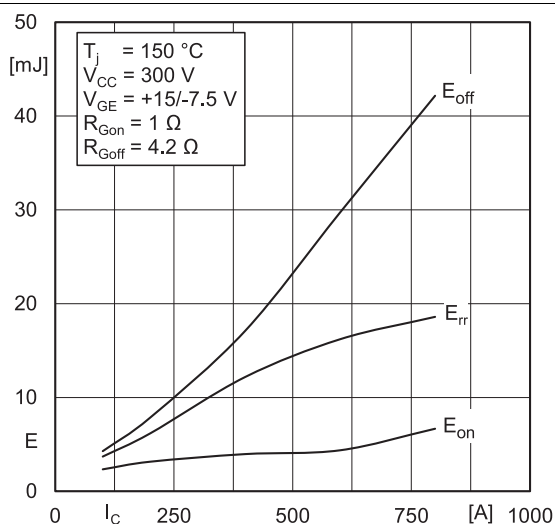


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

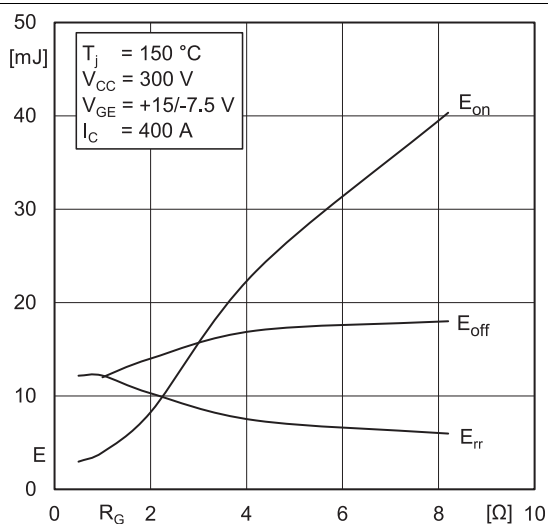


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

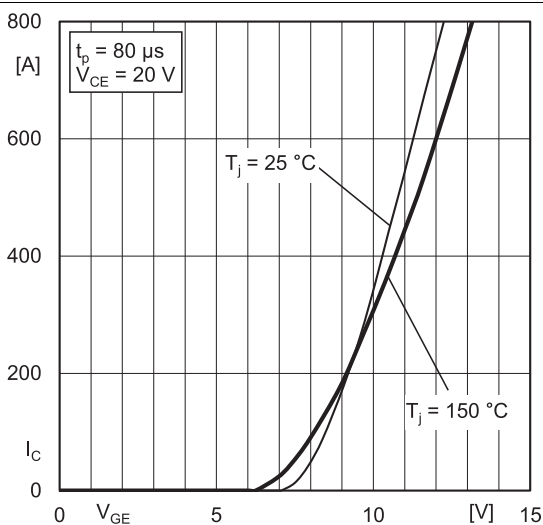


Fig. 5: Typ. transfer characteristic

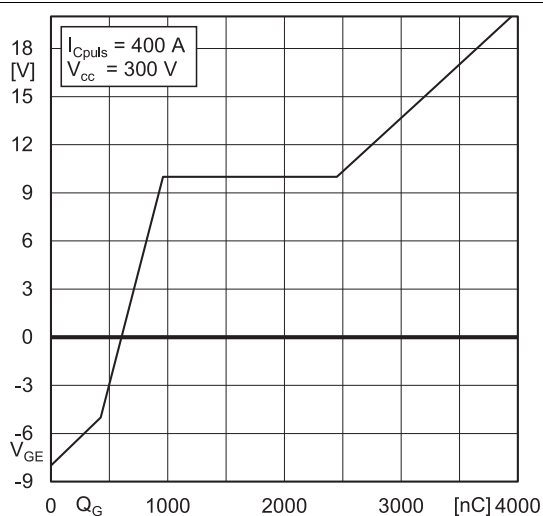
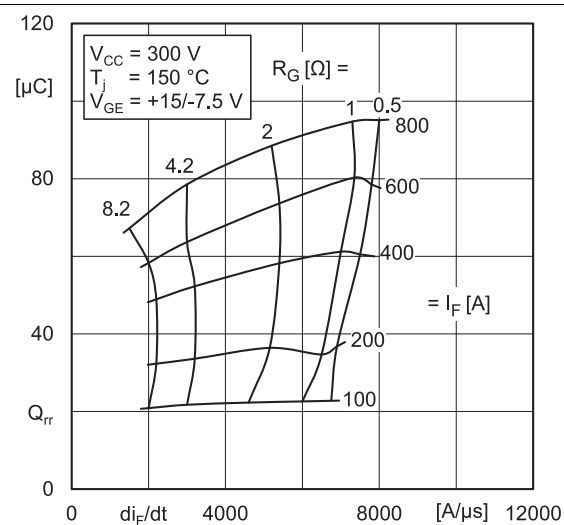
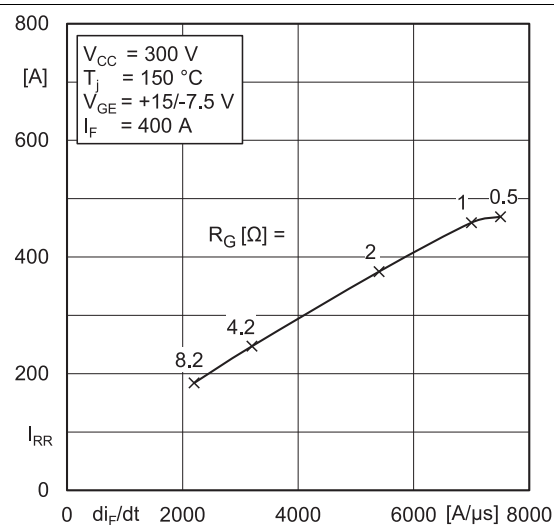
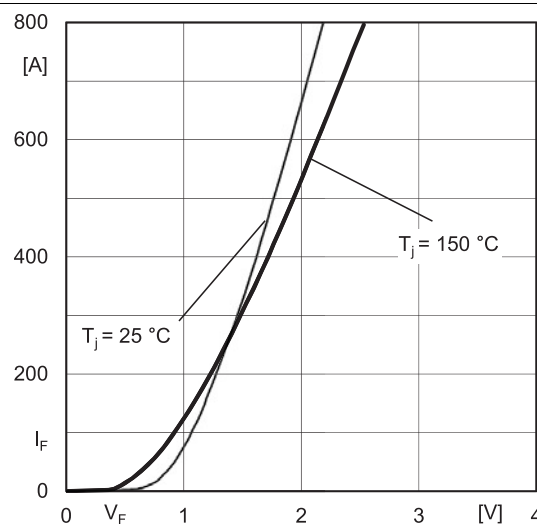
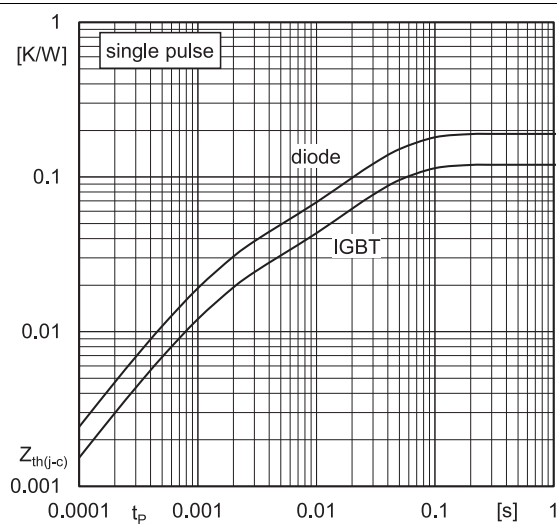
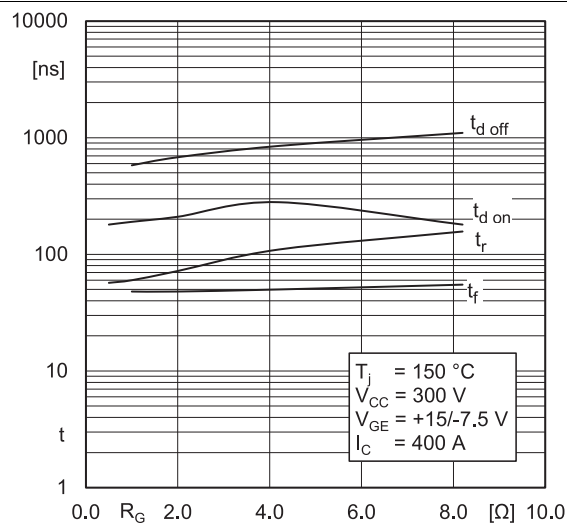
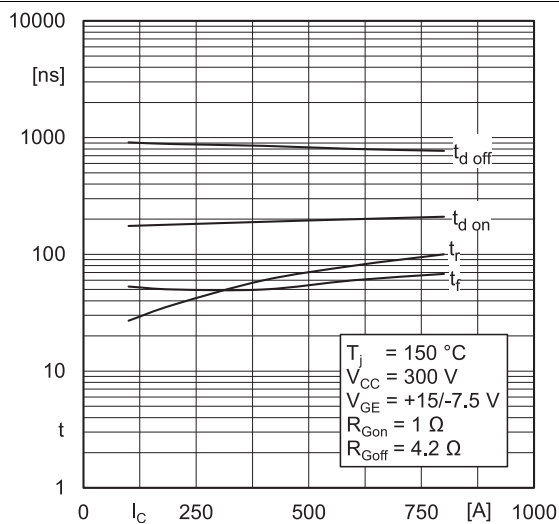
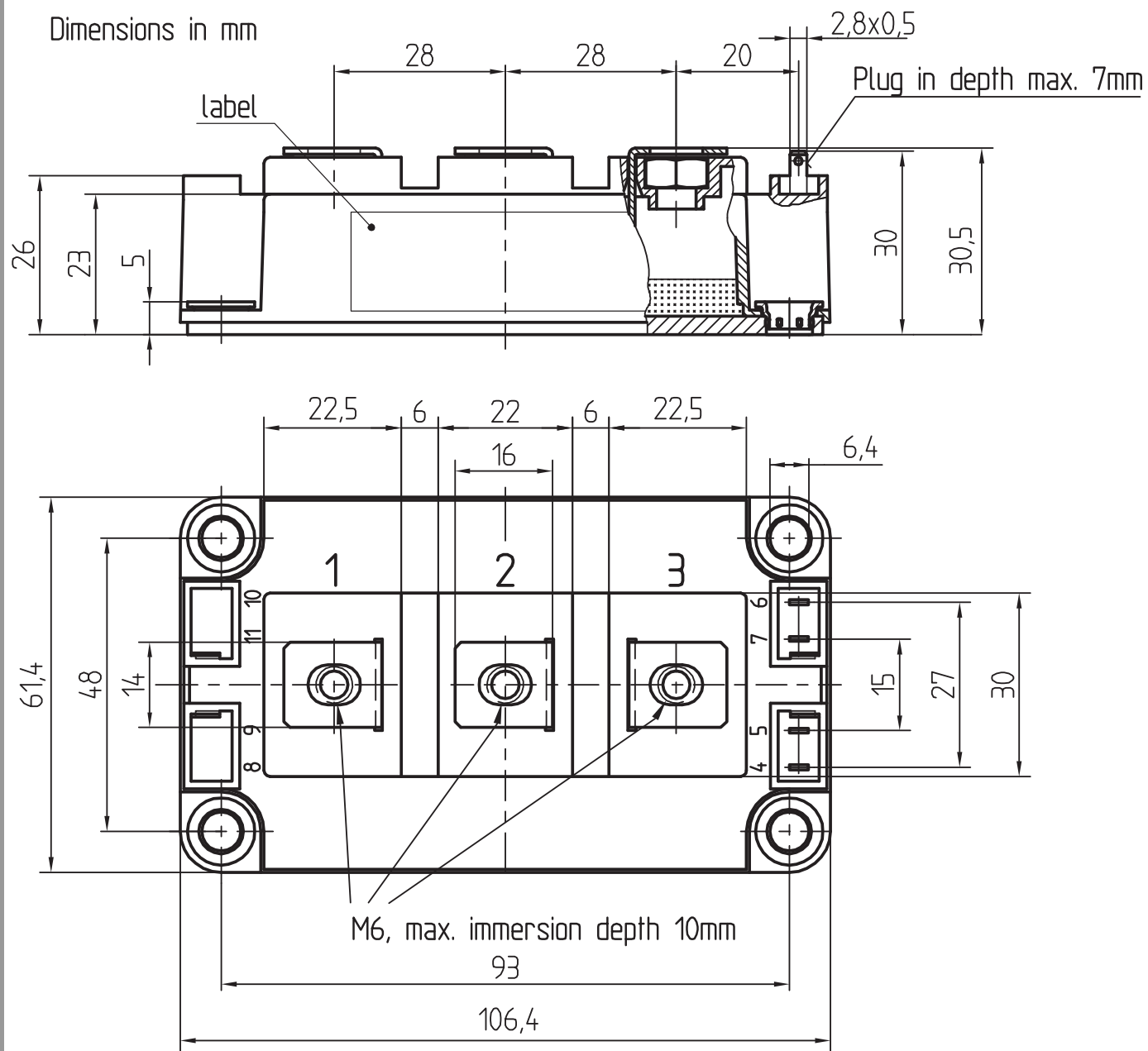


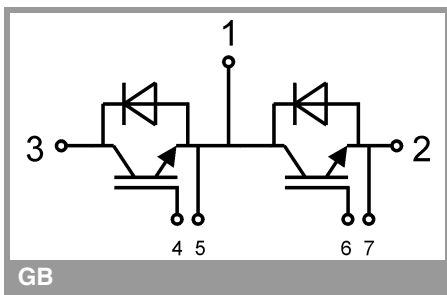
Fig. 6: Typ. gate charge characteristic





General tolerance $\pm 0,5$ mm

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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